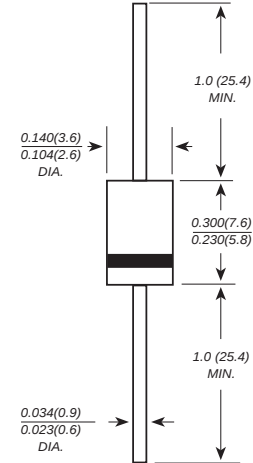


Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed
250°C/10 seconds at terminals

DO-15



Dimensions in inches and (millimeters)

Mechanical Data

Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750,Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0116 ounce, 0.33 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MUR 205	MUR 210	MUR 220	MUR 240	MUR 250	MUR 260	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	500	600	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	350	420	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	500	600	V
Maximum average forward rectified current at T _c =110°C	I _(AV)	2.0						A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	50						A
Maximum instantaneous forward voltage per diode at 2.0A	V _F	1.0			1.3	1.8		V
Maximum DC reverse current at rated DC blocking voltage	T _A =25°C T _A =125°C I _R	5.0 200						u A
Maximum reverse recovery time	T _{rr}	35			50			ns
Typical thermal resistance	R _{qJA}	75.0						°C/W
Operating junction temperature range	T _J	-55 to +150						°C
Storage temperature range	T _{STG}	-55 to +150						°C

Note:1.Reverse recovery time test condition: $I_F=0.5A$ $I_R=1.0A$ $I_{rr}=0.25A$

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

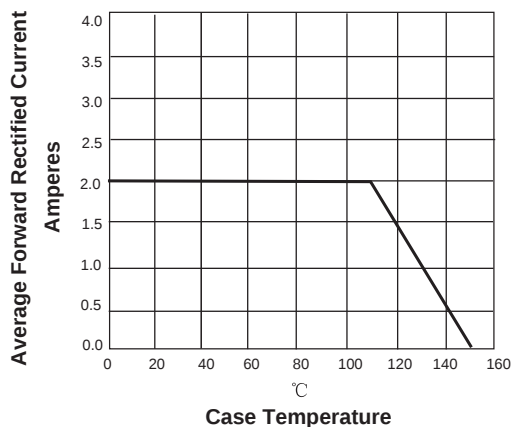


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

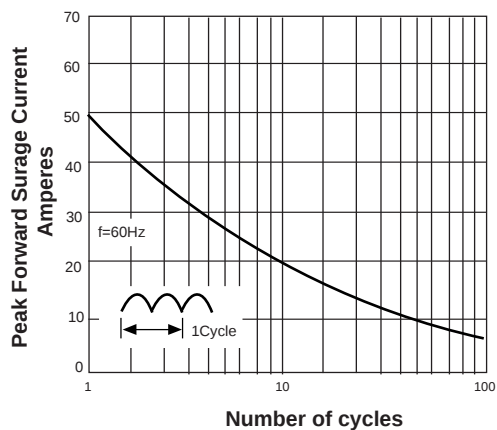


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

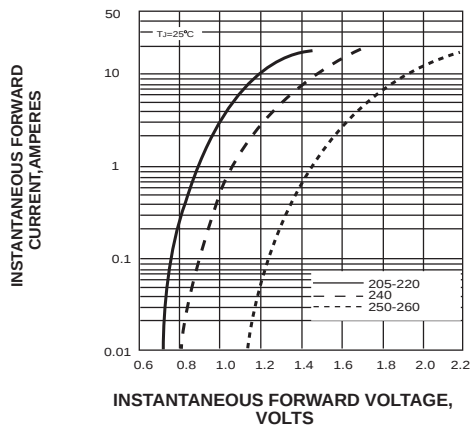
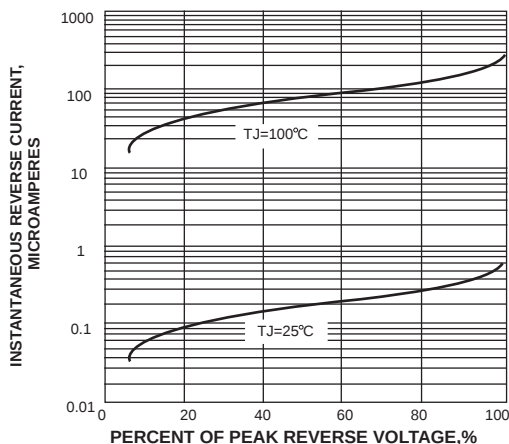
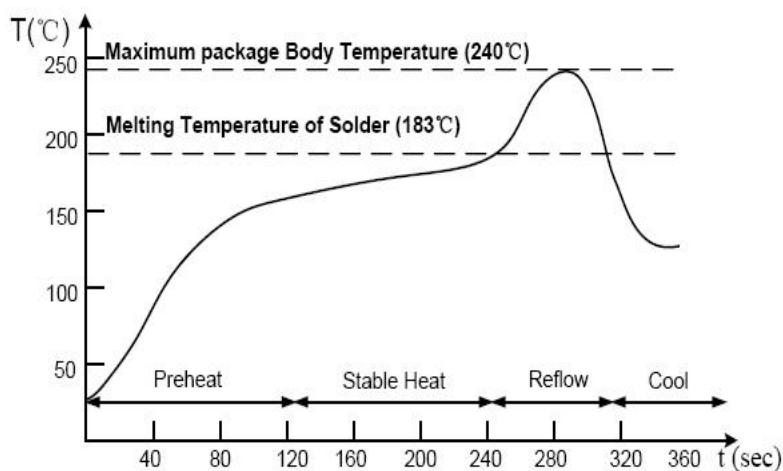


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Suggested Soldering Temperature Profile

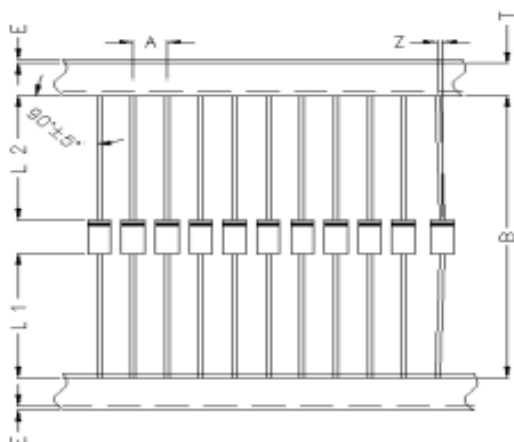


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Taping Specifications



Item	Symbol	Specifications(mm)
Component Pitch	A	5.0±0.5
Inner Tape Pitch	B	52.4±1.5
Component alignment	Z	1.2 Max
Tape width	T	6.0±0.5
Exposed adhesive	E	0.8 Max
Body eccentricity	L1-L2	1.0 Max

Ammunition Package Specifications

Package	Inner Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
DO - 15	255*150*75	3	420*276*312	30